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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet	2	of	2
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Complet if Known

Application Number	10/091,262
Filing Date	03/05/2002
First Named Inventor	Stewart, Steven L
Art Unit	1771
Examiner Name	
Attorney Docket Number	US 01.012

U. S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

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Examiner Initials*	Cite No.	Foreign Patent Document Country Code ³ Number ⁴ Kind Code ⁵ (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear	
USE		JP 05347474 A	12-27-1993	Matsushita Electric Ind		
↓		JP 57068053 A	04-26-1982	Seiko Epson Corp		
		JP 04352491 A	12-7-1992	Matsushita Electric Ind		

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REFERENCE DESIGNATION

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	AB	6084781	7/4/2000	Klein	
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	AG	6265776	7/24/2001	Gilleo	

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	Document No.	Country	Date*	Date* Cited in Foreign P.O.	English Translation Yes No
	FA				
	FB				

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		Date* Cited in Foreign P.O.	English Translation Yes No
	PA Adamson, S.J., "CSP and flip chip underfill," Advanced Packaging, June 2001, pp. 37-44.		
	PB Johnson, Zane, "BGA Underfills" Advanced Packaging, December 2001, pp. 29-33		
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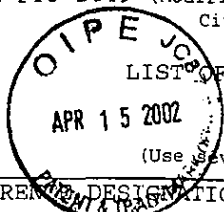
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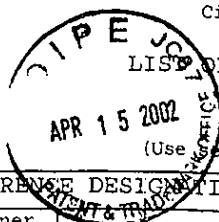
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	PAA	Yamaji, Y., "A proposal: the Assessing Method of the CSP's Mechanical Reliability on Board," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 1, First Quarter 2000, pp. 138-145			
	PBB	Goyal, S, "Methods for Realistic Drop-Testing," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 1, First Quarter 2000, pp. 45-52			
	PCC	Xu, K., "A General Purpose Adhesive for Microelectronic Devices," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 1, First Quarter 2000, pp. 78-84			
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V3C	PEE	Gilleo, K., "New Generation Underfills Power The 2 nd Flip Chip Revolution," [internet] URL: http://www.cooksonsemi.com/tech_art/polysolder.htm	!		
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